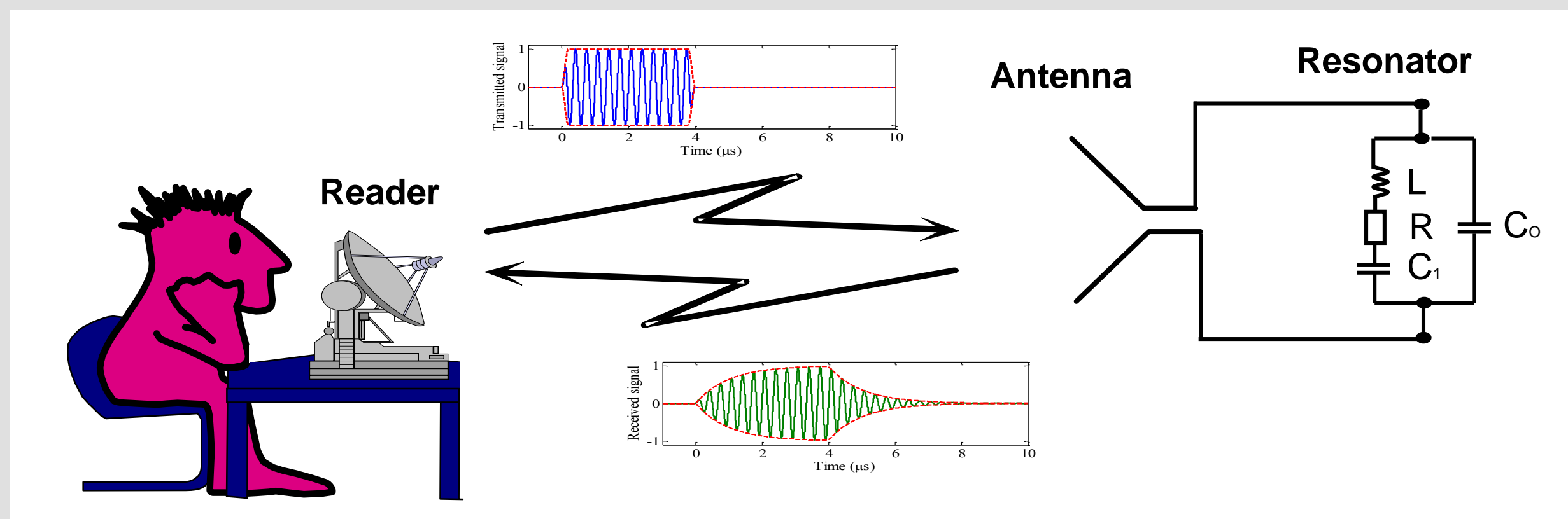


Motivation

- Ubiquitous sensing for the internet of things.
- Monitoring in harsh environments.
- Chipless design gives high temperature compatibility.
- Frequency shift sensing using high-Q resonator.
- Integrated antenna + sensor concept.
- Low complexity, low cost.

Wireless measurement scheme

- Frequency shift measurement due to physical variable.
- Burst signal from interrogation unit excites the resonator.
- The decaying response is analyzed.



Force sensing mechanism

- Perturbation of the evanescent field of the resonator is caused by relative motion of a conductor.

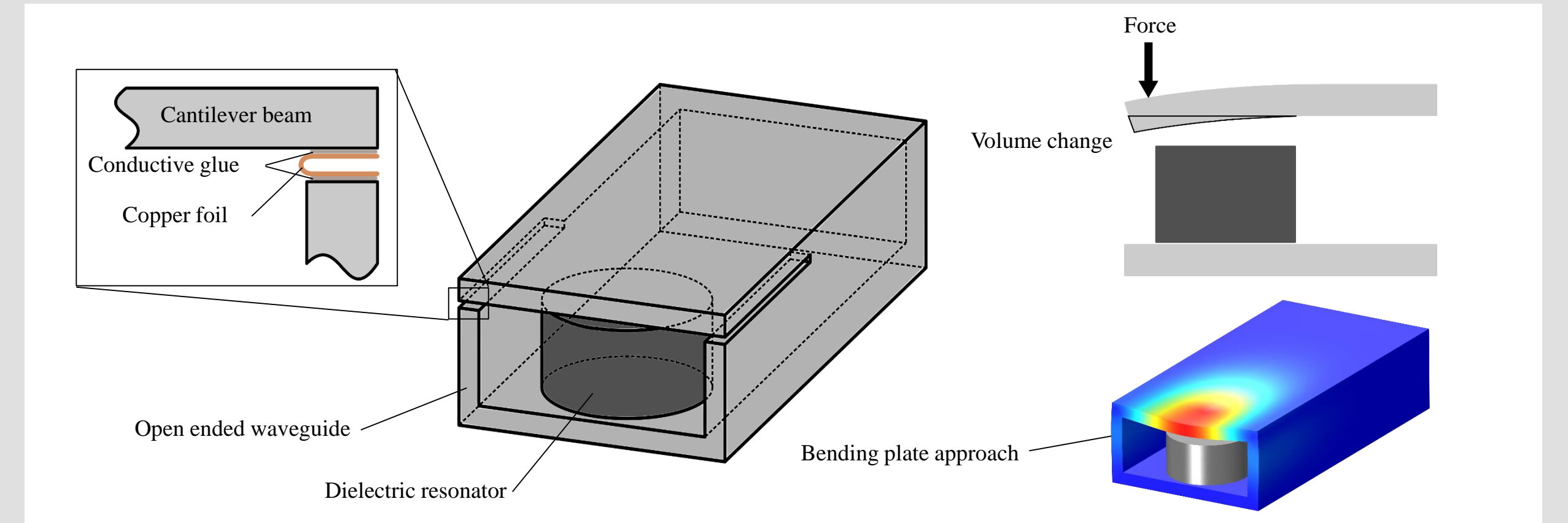


Figure 4: A modified waveguide with slits (left) to allow a cantilever behavior (top right). An uncut bending plate design (bottom right).

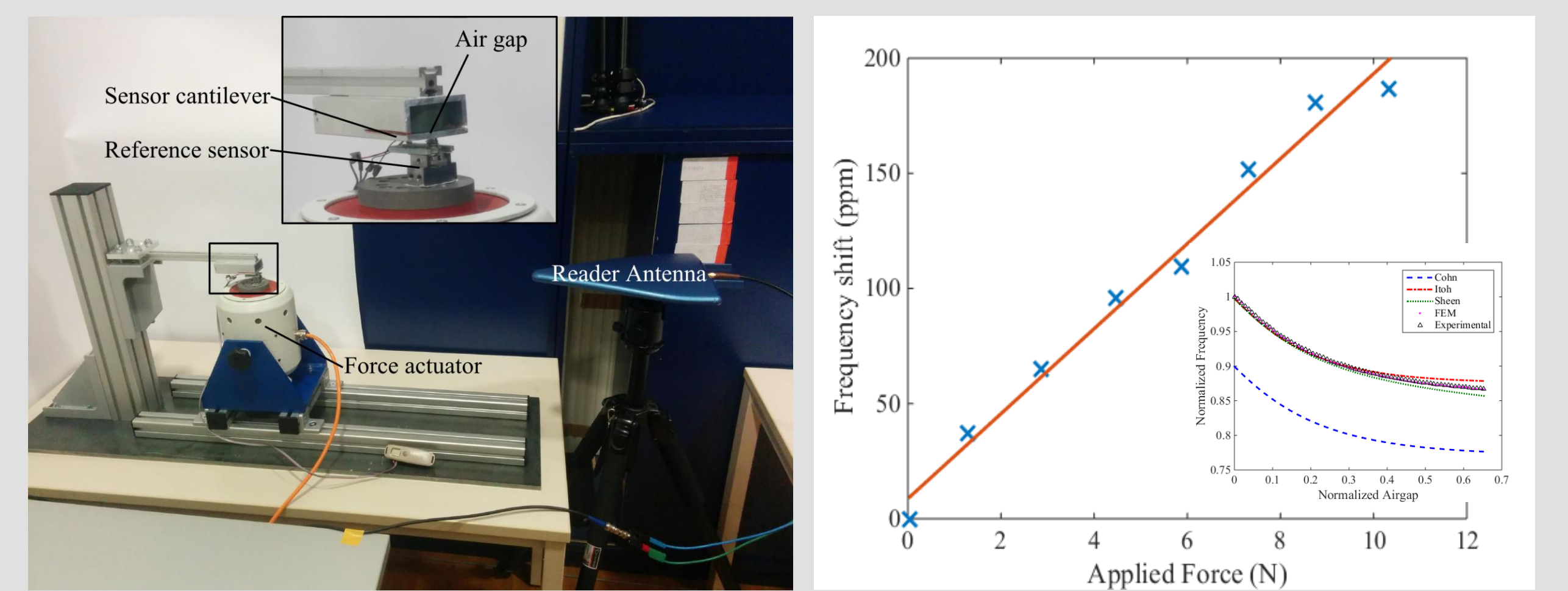


Figure 5: Experimental sensor characterization setup(left). Force-frequency shift transfer function @ 2.46 GHz (right). Theoretical PPDR frequency perturbation action (right insert).

Sensor design

- Dielectric resonator (TE_{01δ} mode) in evanescent open ended waveguide.
- Frequency perturbation modelled as PPDR.

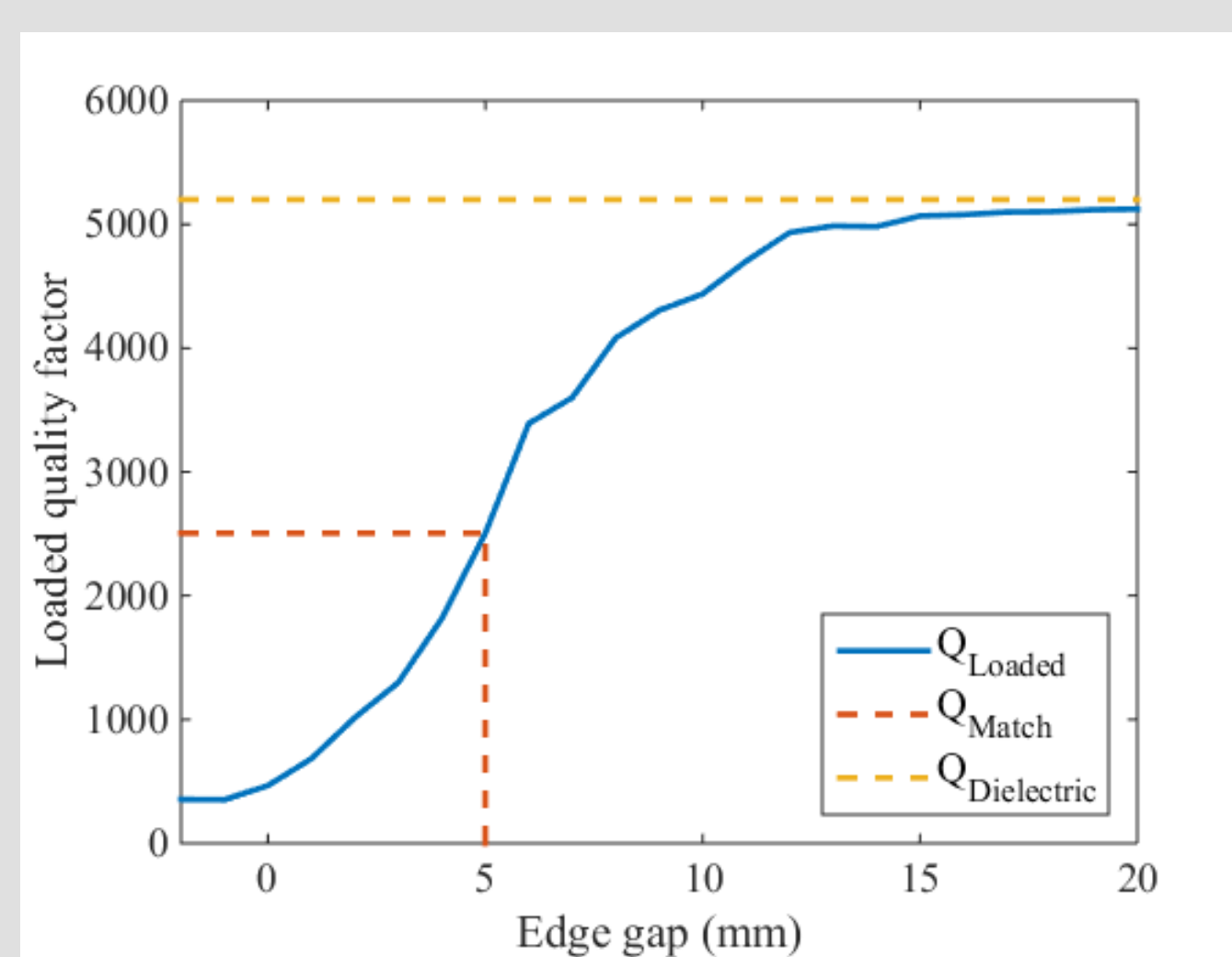


Figure 1: Radiation and dielectric Q matching from simulation.

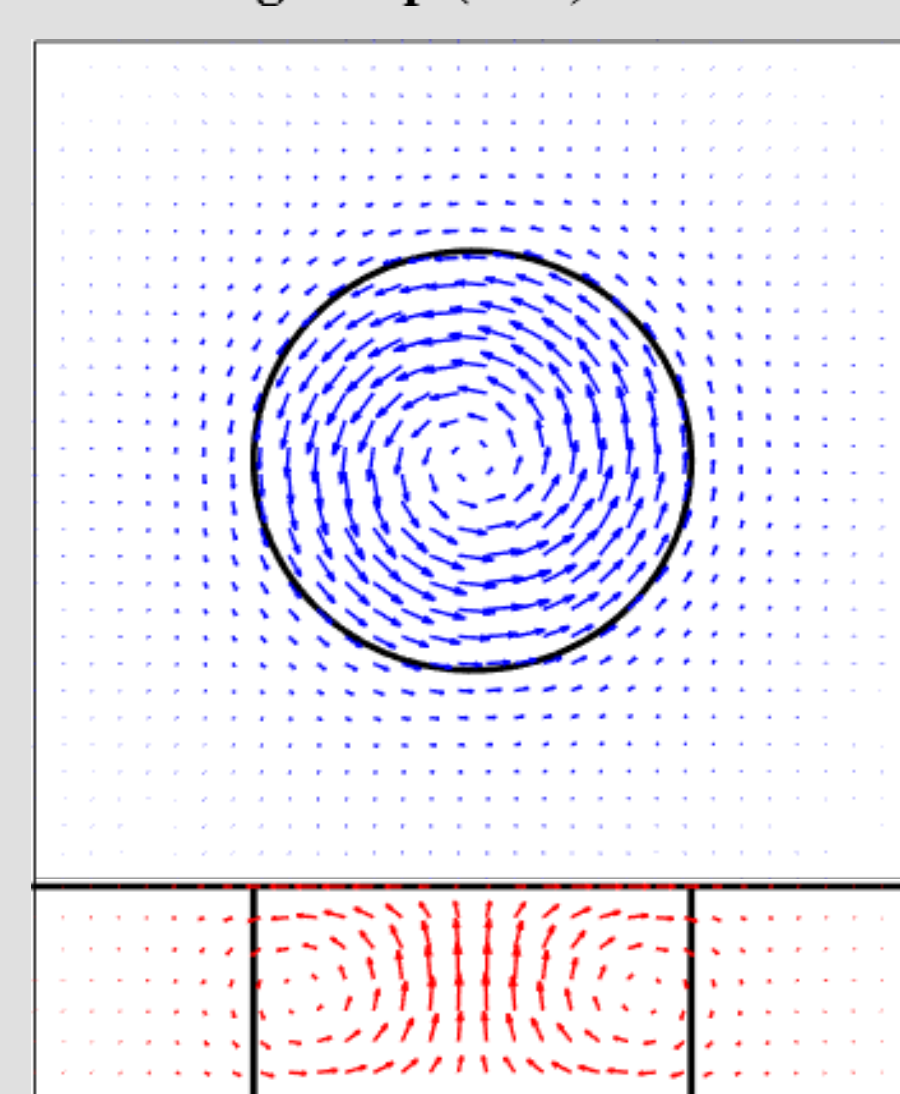
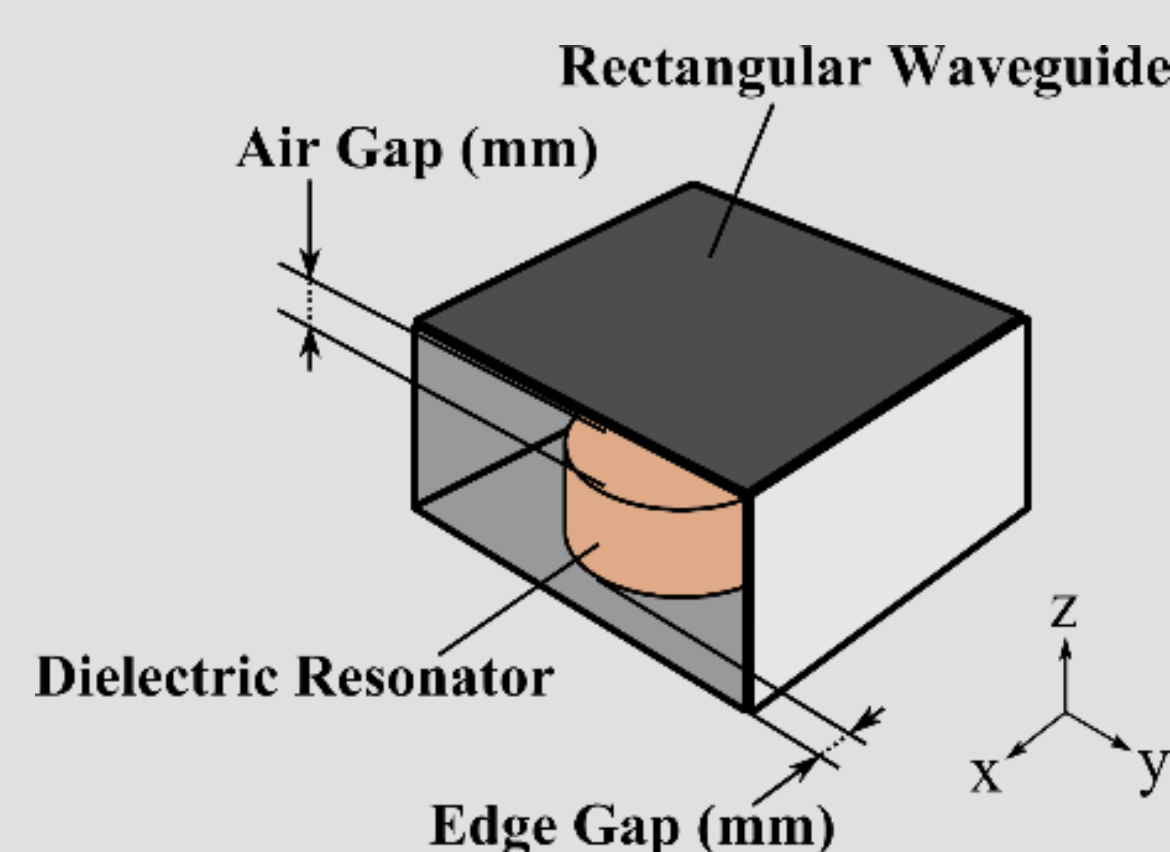


Figure 2: E and H field plots of the TE_{01δ} mode.

- Maximum coupling is achieved when $Q_{rad} = Q_{other}$

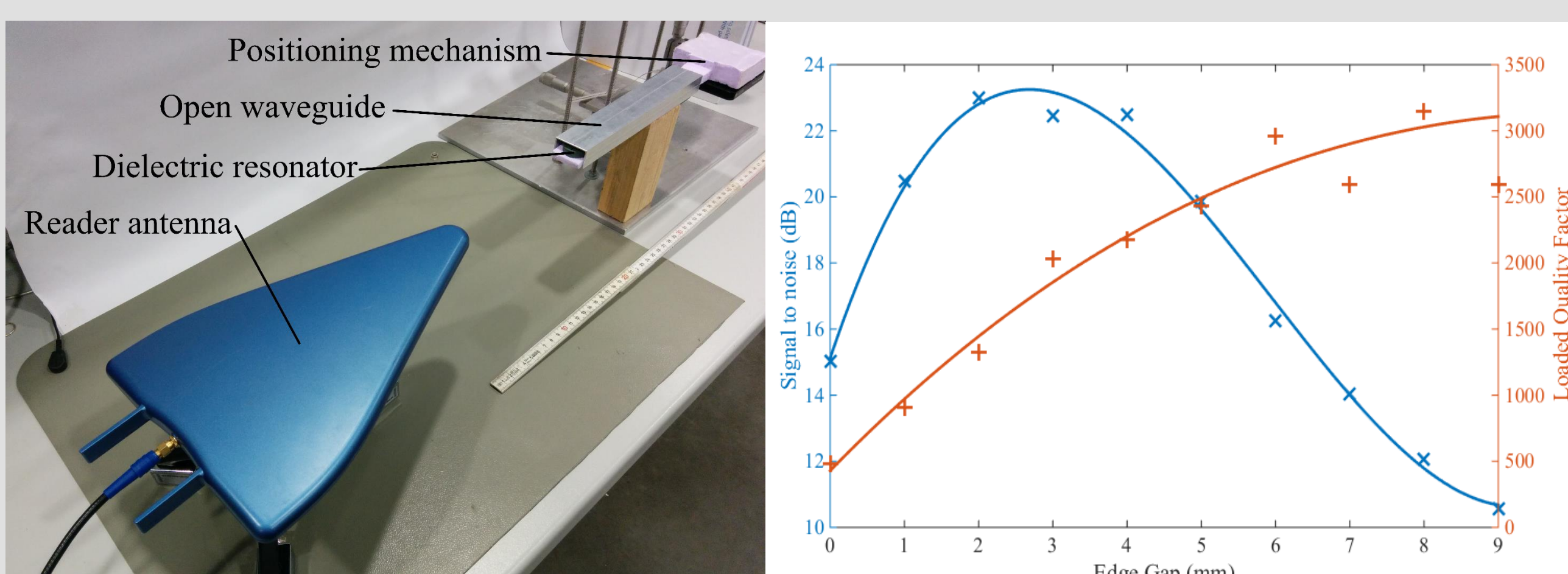


Figure 3: Experimental determination of the maximum SNR 'edge gap'.

Far field characterization

- 2 dBi gain as an antenna.
- < 1 ppm frequency tracking resolution @ 30 cm, 2.45 GHz.
- Up to 5 m range with 5 dBi interrogation antenna.

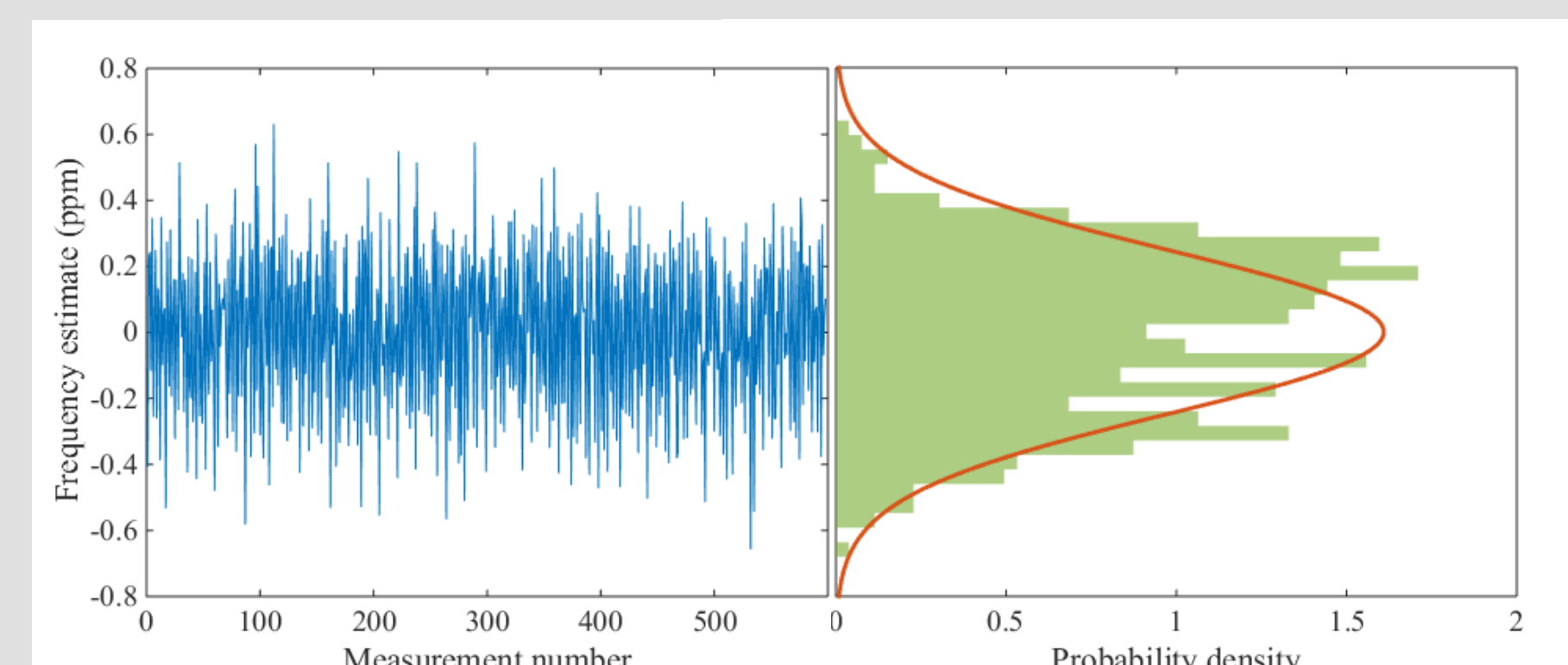


Figure 6: Frequency measurement @ 1k samp/sec with spread probability (right).

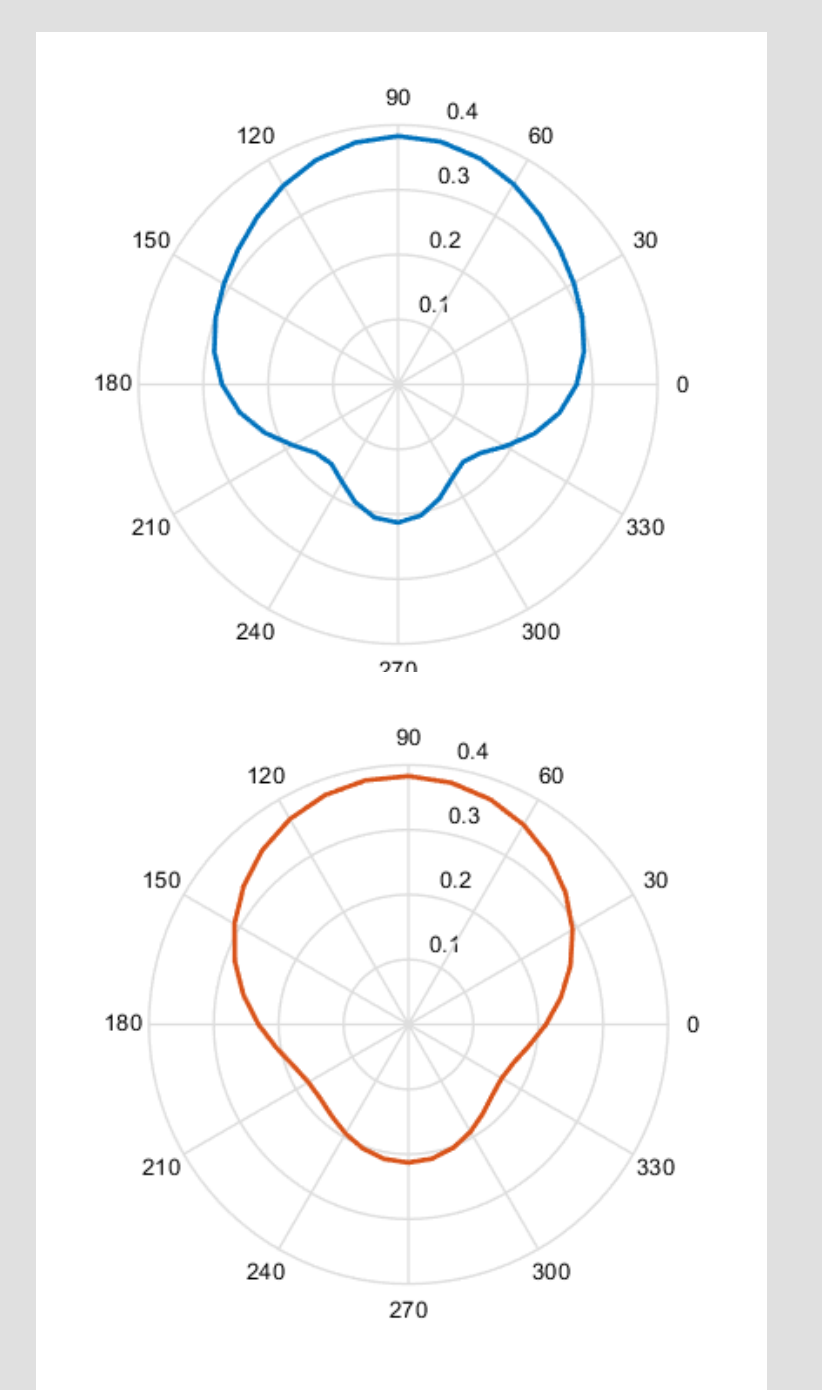


Figure 7: Horizontal (top) and vertical (bottom) radiation profiles.

Acknowledgements

- Funding: DFG GRK1322: "Micro Energy Harvesting"
- T-Ceram for sample resonators.
- Theodor Rinas for the force characterization rig.

References

- [1] D. Kajfez *et al.*, Dielectric resonators, Second edi. 1986
- [2] G. Scholl *et al.*, US Patent 1997,US5691698.
- [3] H. Cheng *et al.*, IEEE APSURSI, 2011, pp. 1350–1353.
- [4] B. Kubina *et al.*, IEEE SENSORS, 2013, pp. 1–4.